

Tyrone Camarero Specifications

Tyrone®

Camarero SSI100C3S-445

Key features

Database Applications, Backup Storage, Cold Storage, Data Warehousing, Archiving

- Single Socket P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable processors. Up to 270W TDP.
- Intel® C621A
- 8 DIMM slots, Up to 2TB: 8x 256 GB DRAM, Up to 3TB: 4x 256 GB DRAM and 4x 512 GB PMem, Memory Type: 3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM
- 2 PCI-E 4.0 x16 (LP) slots, 2 PCI-E 4.0 x8 (LP) slots
- Intel® Ethernet Controller X550 2x 10GbE RJ45
- 45x Top-loading hot-swap 3.5" SAS3/SATA3 drive bays, 2x Hot-swap 2.5" SATA drive bays (rear), Onboard 1x NVMe/SATA M.2; 2x Hot-swap 2.5" SATA3/NVMe (rear, optional)
- 5x (8cm x8cm x3.8cm) heavy duty fans with optimal fan speed control
- Redundant Platinum 1600W Power Supply



Processor/Cache		Front Panel	
Processor	Single Socket P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable processors. Up to 270W TDP.	LEDs	Device Activity, LAN 1 Activity, LAN 2 Activity, Power Failure LED, Power status, System information
Chipset	Intel® C621A chipset	Buttons	Power On/Off button, System Reset
System Memory		Drive Bays	
Memory Capacity	8 DIMM slots, Up to 2TB: 8x 256 GB DRAM, Up to 3TB: 4x 256 GB DRAM and 4x 512 GB PMem, Memory Type: 3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM	HDD Bays	45x 3.5" hot-swap SATA/SAS drive bays
Expansion Slots		Power Supply	
PCI-Express	2 PCI-E 4.0 x16 (LP) slots, 2 PCI-E 4.0 x8 (LP) slots	Redundant Platinum 1600W Power Supply	
Integrated Onboard		Cooling System	
SATA	SATA3 (6Gbps) via C621A Chipset; RAID 0, 1, 5, 10 support	5x (8cm x8cm x3.8cm) heavy duty fans with optimal fan speed control	
SAS	SAS3 (12Gbps) via Broadcom 3808 (IT mode)	Form Factor	
Network Connectivity	2x 10GbE BaseT with Intel® X550	Form Factor	4U Rackmount
Add-on Options		Dimensions:	Height : 7" (178mm), Width : 17.2" (437mm), Depth : 26" (660mm)
Optical Drive	Optional	Email : info@tyronesystems.com For more/current product information, visit www.tyronesystems.com	

Intel, the Intel logo, the Intel Inside logo, Xeon, and Intel Xeon Phi are trademarks of Intel Corporation in the U.S. and/or other countries. Specifications subject to change without notice. Picture used for representation purpose only and the actual product may differ in looks. All other brands and names are the property of their respective owners.